

REMARKS

The Specification has been amended to correct an obvious error that does not constitute new matter. One skilled in the art would not only recognize the existence of the error in the specification, but also the appropriate correction. In the dual damascene process, described on pages 13-15 of the Specification and with reference to Figs. 13-21, the error is that the CMP process stops at "polymer layer 5", not at "seed layer 202". CMP removes not only the "plated metal 210" above the polymer, but also "seed layer 202" and "adhesion layer 200" above the polymer. Note that the triple damascene process, described on pages 15-16 and with reference to Figs. 22-27, correctly shows the CMP removal of the seed layer/adhesion layer 234 stopping at the polymer layer 230 (see especially Fig. 26). Corrected drawing figures have already been submitted with the divisional patent application.

All Claims are believed to be in condition for Allowance, and that is so requested.

Allowance of all Claims is requested.

It is requested that should the Examiner not find that the Claims are now Allowable that the Examiner call the undersigned at 765 4530866 to overcome any problems preventing allowance.

Respectfully submitted,

A handwritten signature in black ink, appearing to be 'SBA', written in a cursive style.

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